

CLAIMSWhat is claimed is:

1. A process for manufacturing macroelectronics comprising the steps of:  
producing thin film active electronics on separate carrier substrates; and  
combining said substrates using anisotropic electrical conductors or light  
guides.
2. The process of claim 1 wherein one of said substrates is a flexible foil.
3. The process of claim 1 wherein one of said substrates is a rigid plate.
4. The process of claim 2 wherein the material for one of said substrates is  
plastic.
5. The process of claim 3 wherein the material for one of said substrates is  
plastic.
6. The process of claim 2 wherein the material for one of said substrates is  
glass.
7. The process of claim 3 wherein the material for one of said substrates is  
glass.
8. The process of claim 2 wherein the material for one of said substrates is  
metal.
9. The process of claim 3 wherein the material for one of said substrates is  
metal.
10. The process of claim 1 wherein the thin film active electronics are  
produced continuously on separate carrier substrates.
11. The process of claim 4 wherein organic light emitting diodes are formed  
on the plastic substrate.
12. The process of claim 5 wherein organic light emitting diodes are formed  
on the plastic substrate.
13. The process of claim 6 wherein organic light emitting diodes are formed  
on the glass substrate.
14. The process of claim 7 wherein organic light emitting diodes are formed  
on the glass substrate.

5

10

15

20

25

30

Sub  
B3

T06020" E5T24960

Sub  
a1Sub  
B3

15. The process of claim 6 wherein thin film transistors are formed on the glass substrate.

16. The process of claim 7 wherein thin film transistors are formed on the glass substrate.

5 17. A process of making electronic circuits comprising the steps of:  
forming at least two active circuits on separate carrier substrates; and  
combining said active circuits by connecting them with a material which  
conducts in only a single direction.

10 18. A method of manufacturing an electronic display comprising the steps  
of:  
depositing a transparent conductor on a transparent substrate;  
forming a thin film organic light emitting diode circuit on said  
transparent conductor;  
forming a thin film transistor circuit; and  
15 laminating said circuits to each other.

19. The method of claim 18 wherein said laminating step uses an adhesive  
anisotropic conductor.

20. The method of claim 19 wherein the conductor is an electrical or optical  
conductor.

20 21. The method of claim 19 wherein the bonding layer is the conductor.

22. A method of manufacturing an electronic circuit comprising the steps of:  
forming a first active circuit on a first plane;  
forming a second active circuit on a second plane; and  
co-laminating said first and second planes with an anisotropic conductor  
25 in between.

09647193.070301  
T03070301